



# **CAN TRANSCEIVER**

#### **FEATURES**

- Drop-In Improved Replacement for the PCA82C250 and PCA82C251
- Bus-Fault Protection of ±36 V
- Meets or Exceeds ISO 11898
- Signaling Rates<sup>(1)</sup> up to 1 Mbps
- High Input Impedance Allows up to 120 SN65HVD251 Nodes on a Bus
- Bus Pin ESD Protection Exceeds 14 kV HBM
- Unpowered Node Does Not Disturb the Bus
- Low Current Standby Mode . . . 200 μA Typical
- Thermal Shutdown Protection

- Glitch-Free Power-Up and Power-Down Bus Protection For Hot-Plugging
- DeviceNet Vendor ID # 806

#### **APPLICATIONS**

- CAN Data Buses
- Industrial Automation
  - DeviceNet™ Data Buses
  - Smart Distributed Systems (SDS™)
- SAE J1939 Standard Data Bus Interface
- NMEA 2000 Standard Data Bus Interface
- ISO 11783 Standard Data Bus Interface

#### **DESCRIPTION**

The SN65HVD251 is intended for use in applications employing the Controller Area Network (CAN) serial communication physical layer in accordance with the ISO 11898 Standard. The SN65HVD251 provides differential transmit capability to the bus and differential receive capability to a CAN controller at speeds up to 1 megabits per second (Mbps).

Designed for operation in harsh environments, the device features cross-wire, over-voltage and loss of ground protection to  $\pm 36$  V. Also featured are over-temperature protection as well as -7 V to 12 V common-mode range, and tolerance to transients of  $\pm$  200 V. The transceiver interfaces the single-ended CAN controller with the differential CAN bus found in industrial, building automation, and automotive applications.

Rs, pin 8, provides for three different modes of operation: high-speed, slope control, or low-power mode. The high-speed mode of operation is selected by connecting pin 8 to ground, allowing the transmitter output transistors to switch as fast as possible with no limitation on the rise and fall slope. The rise and fall slope can be adjusted by connecting a resistor to ground at pin 8; the slope is proportional to the pin's output current. Slope control with an external resistor value of 10 k $\Omega$  gives ~ 15 V/us slew rate; 100 k $\Omega$  gives ~ 2 V/us slew rate.

If a high logic level is applied to the Rs pin 8, the device enters a low-current standby mode during which the driver is switched off and the receiver remains active. The local protocol controller reverses this low-current standby mode when it needs to transmit to the bus.

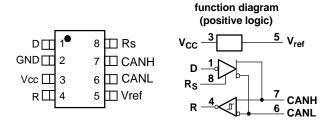
The SN65HVD251 may be used in CAN, DeviceNet<sup>™</sup> or SDS<sup>™</sup> applications with the Texas Instruments' TMS320F241 and TMS320F243 DSPs with CAN 2.0B controllers.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DeviceNet is a trademark of Allen-Bradley. SDS is a trademark of Honeywell.





#### (1)ORDERING INFORMATION

PART NUMBER	PACKAGE	MARKED AS
SN65HVD251D	8-pin SOIC (Tube)	VP251
SN65HVD251DR	8-pin SOIC (Tape & Reel)	VP251
SN65HVD251P	8-pin DIP	65HVD251

(1) (1) The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

# ABSOLUTE MAXIMUM RATINGS(1),(2)

			SN65HVD251
Supply voltage range, V <sub>CC</sub>			-0.3 V to 7V
Voltage range at any bus terminal (0	-36 V to 36 V		
Transient voltage per ISO 7637, pul	±200 V		
Input voltage range, V <sub>I</sub> (D, Rs, or R)			-0.3 V to V <sub>CC</sub> + 0.5
•	Liver on Dady Madel (3)	CANH, CANL and GND	14 kV
Electrostatic discharge	Human Body Model (3)	All pins	6 kV
	Charged-Device Model (4)	All pins	1 kV
Continuous total power dissipation			(see Dissipation Rating Table)
Storage temperature range, T <sub>stg</sub>			-65C to 150°C
Lead temperature 1,6 mm (1/16 inch	260°C		

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
- (3) Tested in accordance with JEDEC Standard 22, Test Method A114-A.
- (4) Tested in accordance with JEDEC Standard 22, Test Method C101.

#### ABSOLUTE MAXIMUM POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	T <sub>A</sub> = 25°C POWER RATING	DERATING FACTOR <sup>(1)</sup> ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
SOIC (D)	Low-K <sup>(2)</sup>	600 mW	4.4 mW/°C	312 mW	120 mW
SOIC (D)	High-K <sup>(3)</sup>	963 mW	7.7 mW/°C	501 mW	193 mW
DDID (D)	Low-K <sup>(2)</sup>	984 mW	7.8 mW/°C	512 mW	197 mW
PDIP (P)	High-K <sup>(3)</sup>	1344 mW	10.8 mW/°C	699 mW	269 mW

- (1) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.
- 2) In accordance with the Low-K thermal metric definitions of EIA/JESD51-3.
- 3) In accordance with the High-K thermal metric definitions of EIA/JESD51-7.

#### THERMAL CHARACTERISTICS

	PARAMETER	TEST CONDITIONS	VA	VALUE		UNITS
			MIN	TYP	MAX	
Γ.	Θ <sub>JB</sub> Junction-to-board thermal resistance	D		78.7		°C/W
Ľ		P		56.5		°C/VV



# THERMAL CHARACTERISTICS (continued)

	PARAMETER	TEST CONDITIONS		VALUE			UNITS
				MIN	TYP	MAX	
	Junction-to-board thermal resistance		D		44.6		°C/W
ΘJC	Junction-to-board thermal resistance		Р		54.5		-C/VV
		$V_{CC}$ = 5 V, Tj = 27 °C, RL = 60 R <sub>S</sub> at 0 V, Input to D a 500-kH 50% duty cycle square wave	0Ω, Iz			97.7	mW
P <sub>D</sub> Device power dissipation		V <sub>CC</sub> = 5.5 V, Tj = 130°C, RL = R <sub>S</sub> at 0 V, Input to D a 500-kH duty cycle square wave	: 60Ω, Iz 50%			142	mW
T <sub>SD</sub>	Thermal shutdown junction temperature				165		°C

#### RECOMMENDED OPERATING CONDITIONS

over recommended operating conditions (unless otherwise noted).

PARAMETER		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.5		5.5	V
Voltage at any bus terminal (separately or common	mode) V <sub>I</sub> or V <sub>IC</sub>	-7 <sup>(1)</sup>	•	12	V
High-level input voltage, V <sub>IH</sub>	D input	0.7 V <sub>CC</sub>			V
Low-level input voltage, V <sub>IL</sub>	D input			0.3 V <sub>CC</sub>	V
Differential input voltage, V <sub>ID</sub>	·	-6		6	V
Input voltage to Rs, V <sub>I(Rs)</sub>		0	,	V <sub>cc</sub>	V
Input voltage at Rs for standby, V <sub>I(Rs)</sub>		0.75 V <sub>CC</sub>	•	V <sub>CC</sub>	V
Rs wave-shaping resistance		0		100	kΩ
Himb lavel autout aumant I	Driver	-50			A
High-level output current, I <sub>OH</sub>	Receiver	-4			mA
Levelevel enterit enterit	Driver			50	A
Low-level output current, I <sub>OL</sub>	Receiver			4	mA
Operating free-air temperature, T <sub>A</sub>		-40		125	°C
handing to an author. T	PDIP Package			145	00
Junction temperature, T <sub>j</sub>	SOIC Package			150	°C

<sup>(1)</sup> The algebraic convention, in which the least positive (most negative) limit is designated as minimum is used in this data sheet.

## **DRIVER ELECTRICAL CHARACTERISTICS**

over recommended operating conditions (unless otherwise noted).

	PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
.,	Pur cutaut valtage (Deminent)	CANH	Figure 1 & Figure 2,	2.75	3.5	4.5	
$V_{O(D)}$	Bus output voltage (Dominant)	CANL	D at 0 V Rs at 0 V	0.5		2	V
\ <u></u>	Bus output voltage	CANH	Figure 1 & Figure 2, D at	2	2.5	3	V
$V_{O(R)}$	(Recessive)	, OANE CC.	2	2.5	3		
V <sub>OD(D)</sub>	Differential output voltage (Domi	nant)	Figure 1, D at 0 V, Rs at 0 V	1.5	2	3	V
V <sub>OD(D)</sub>	Differential output voltage (Domi	nant)	Figure 2 & Figure 3 , D at 0 V, Rs at 0 V	1.2	2	3.1	V
V <sub>OD(R)</sub>	Differential output voltage (Rece	ssive)	Figure 1 & Figure 2 , D at 0.7 V <sub>CC</sub>	-120		12	mV
$V_{OD(R)}$	Differential output voltage (Rece	ssive)	D at 0.7 V <sub>CC</sub> , no load	-0.5		0.05	٧
V <sub>OC(pp)</sub>	Peak-to-peak common-mode ou	tput voltage	Figure 9, Rs at 0 V		600		mV
I <sub>IH</sub>	High-level input current, D Input		D at 0.7 V <sub>CC</sub>	-40		0	μA
I <sub>IL</sub>	Low-level input current, D Input		D at 0.3 V <sub>CC</sub>	-60		0	μΑ

<sup>(1)</sup> All typical values are at 25°C and with a 5-V supply.



# **DRIVER ELECTRICAL CHARACTERISTICS (continued)**

over recommended operating conditions (unless otherwise noted).

	PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
	Short-circuit steady-state output current		Figure 11, V <sub>CANH</sub> at -7 V, CANL Open	-200			
I <sub>OS(SS)</sub>			Figure 11, V <sub>CANH</sub> at 12 V, CANL Open	,		2.5	0
			Figure 11, V <sub>CANL</sub> at -7 V, CANH Open	-2	•		mA
			Figure 11, V <sub>CANL</sub> at 12 V, CANH Open	•		200	
Co	Output capacitance		See receiver input capacitance				
l <sub>oz</sub>	High-impedance output cur	rent	See receiver input current				
I <sub>IRs(s)</sub>	Rs input current for standby	,	Rs at 0.75 V <sub>CC</sub>	-10	,		μΑ
I <sub>IRs(f)</sub>	Rs input current for full spe	ed operation	Rs at 0 V	-550		0	μΑ
		Standby	Rs at V <sub>CC</sub> , D at V <sub>CC</sub>			275	μΑ
I <sub>cc</sub>	Supply current	Dominant	D at 0 V, 60Ω load, Rs at 0 V			65	^
		Recessive	D at V <sub>CC</sub> , no load, Rs at 0 V			14	mA

## **DRIVER SWITCHING CHARACTERISTICS**

over recommended operating conditions (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		Figure 4, Rs at 0 V		40	70	
t <sub>pLH</sub>	Propagation delay time, low-to-high-level output	Figure 4, Rs with 10 $k\Omega$ to ground		90	125	
		Figure 4, Rs with 100 k $\Omega$ to ground		500	800	
		Figure 4, Rs at 0 V		85	125	
$t_{pHL}$	Propagation delay time, high-to-low-level output	Figure 4, Rs with 10 k $\Omega$ to ground		200	260	
·		Figure 4, Rs with 100 kΩ to ground		1150	1450	
		Figure 4, Rs at 0 V		45	85	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>pHL</sub> - t <sub>pLH</sub>  )	Figure 4, Rs with 10 k $\Omega$ to ground		110	180	ns
		Figure 4, Rs with 100 k $\Omega$ to ground		650	900	
t <sub>r</sub>	Differential output signal rise time	Figure 4 Do at 0 V	35		100	
t <sub>f</sub>	Differential output signal fall time	Figure 4, Rs at 0 V	35		100	
t <sub>r</sub>	Differential output signal rise time	Figure 4 Denville 40 LO to arroad	100		250	
t <sub>f</sub>	Differential output signal fall time	Figure 4, Rs with 10 kΩ to ground	100		250	
t <sub>r</sub>	Differential output signal rise time	Figure 4. Do with 400 kg to secured	600		1550	
t <sub>f</sub>	Differential output signal fall time	Figure 4, Rs with 100 kΩ to ground	600		1550	
t <sub>en</sub>	Enable time from standby to dominant	Figure 8			0.5	μs

## RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage			750	900	
V <sub>IT-</sub>	Negative-going input threshold voltage	Rs at 0 V, (See Table 1)	500	650		mV
$V_{hys}$	Hysteresis voltage (V <sub>IT+</sub> - V <sub>IT-</sub> )			100		
V <sub>OH</sub>	High-level output voltage	Figure 6, I <sub>O</sub> = -4mA	0.8 Vcc			V
V <sub>OL</sub>	Low-level output voltage	Figure 6, I <sub>O</sub> = 4mA		-	0.2 Vcc	V



# RECEIVER ELECTRICAL CHARACTERISTICS (continued)

over recommended operating conditions (unless otherwise noted).

	PARAMETER		TEST COND	OITIONS	MIN	TYP	MAX	UNIT
	Bus input current		CANH or CANL at 12 V				600	
			CANH or CANL at 12 V, V <sub>CC</sub> at 0 V	Other bus pin at 0 V, Rs at 0 V, D		,	715	μA
'			CANH or CANL at -7 V	at 0.7 V <sub>CC</sub>	-460	•		·
			CANH or CANL at -7 V, V <sub>CC</sub> at 0 V		-340			
Cı	Input capacitance, (CANI-	f or CANL)	Pin-to-ground, V <sub>I</sub> = 0.4 s D at 0.7 V <sub>CC</sub>	Pin-to-ground, $V_I = 0.4 \sin (4E6\pi t) + 0.5 V$ , D at 0.7 $V_{CC}$		20		pF
C <sub>ID</sub>	Differential input capacita	nce	Pin-to-pin, $V_I = 0.4 \sin (4 \cos \theta)$ at 0.7 $V_{CC}$	4E6πt) + 0.5 V, D		10		pF
R <sub>ID</sub>	Differential input resistant	e	D at 0.7 V <sub>CC</sub> , Rs at 0 V		40	,	100	kΩ
R <sub>IN</sub>	Input resistance, (CANH	or CANL)	D at 0.7 V <sub>CC</sub> , Rs at 0 V	D at 0.7 V <sub>CC</sub> , Rs at 0 V			50	kΩ
		Standby	Rs at V <sub>CC</sub> , D at V <sub>CC</sub>				275	μA
I <sub>CC</sub>	Supply current	Dominant	D at 0 V, 60Ω Load, Rs	Load, Rs at 0 V			65	mA
	Recessive		D at V <sub>CC</sub> , No Load, Rs a	at 0 V			14	IIIA

## RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>pLH</sub>	Propagation delay time, low-to-high-level output			35	50	
t <sub>pHL</sub>	Propagation delay time, high-to-low-level output			35	50	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>pHL</sub> - t <sub>pLH</sub>  )	Figure 6			20	
t <sub>r</sub>	Output signal rise time			2	4	ns
t <sub>f</sub>	Output signal fall time			2	4	
t <sub>p(sb)</sub>	Propagation delay time in standby	Figure 12, Rs at V <sub>CC</sub>			500	

## **VREF-PIN CHARACTERISTICS**

over recommended operating conditions (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP MAX	UNIT
Vo	Reference output voltage	-5 μA < I <sub>O</sub> < 5 μA	0.45 V <sub>CC</sub>	0.55 V <sub>CC</sub>	V
		-50 μA < I <sub>O</sub> < 50 μA	0.4 V <sub>CC</sub>	0.6 V <sub>CC</sub>	



## **DEVICE SWITCHING CHARACTERISTICS**

over recommended operating conditions (unless otherwise noted).

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>loop1</sub>	Total loop delay, driver input to receiver output, recessive to dominant	Figure 10, Rs at 0 V		60	100	
		Figure 10, Rs with 10 kΩ to ground		100	150	ns
		Figure 10, Rs with 100 k $\Omega$ to ground		440	800	
t <sub>loop2</sub>	Total loop delay, driver input to receiver output, dominant to recessive	Figure 10, Rs at 0 V		115	150	
		Figure 10, Rs with 10 kΩ to ground		235	290	ns
		Figure 10, Rs with 100 k $\Omega$ to ground		1070	1450	
t <sub>loop2</sub>	Total loop delay, driver input to receiver output, dominant to recessive	Figure 10, Rs at 0 V, V <sub>CC</sub> from 4.5 V to 5.1 V,		105	145	ns

# PARAMETER MEASUREMENT INFORMATION

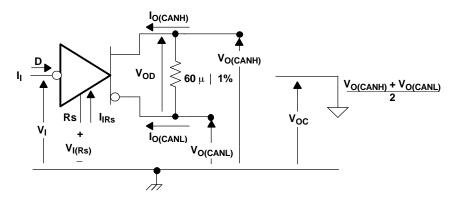


Figure 1. Driver Voltage, Current, and Test Definition

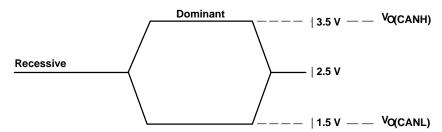


Figure 2. Bus Logic State Voltage Definitions

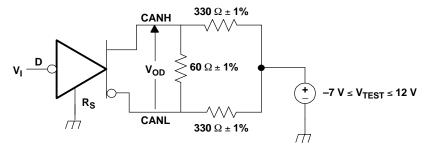


Figure 3. Driver V<sub>OD</sub>



# PARAMETER MEASUREMENT INFORMATION (continued)

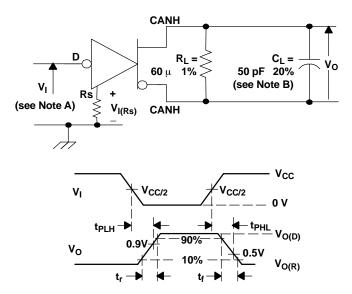


Figure 4. Driver Test Circuit and Voltage Waveforms

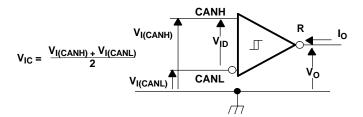
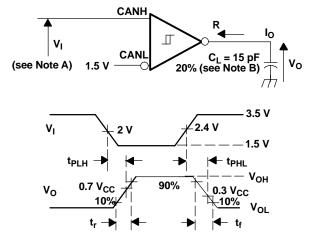


Figure 5. Receiver Voltage and Current Definitions



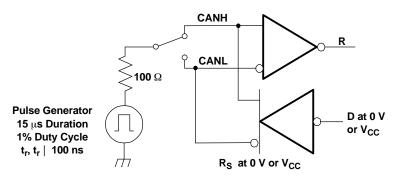
- A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  125 kHz, 50% duty cycle,  $t_r \leq$  6ns,  $t_l \leq$  6ns,  $Z_Q = 50\Omega$ .
- B.  $C_L$  includes instrumentation and fixture capacitance within  $\pm 20\%$ .

Figure 6. Receiver Test Circuit and Voltage Waveforms

open



# PARAMETER MEASUREMENT INFORMATION (continued)



A. This test is conducted to test survivability only. Data stability at the R output is not specified.

open

Figure 7. Test Circuit, Transient Over-Voltage Test

INPUT **MEASURED** OUTPUT R V<sub>CANL</sub>  $|V_{ID}|$ V<sub>CANH</sub> 12 V 11.1 V 900 mV L -6.1 V -7 V 900 mV L  $V_{OL}$ -1 V -7 V 6 V L 12 V 6 V 6 V L -6.5 V -7 V 500 mV Н 11.5 V 12 V 500 mV Н -7 V -1 V 6 V Н  $V_{OH}$ 6 V 12 V 6 V Н

Χ

Н

**Table 1. Receiver Characteristics Over Common Mode Voltage** 

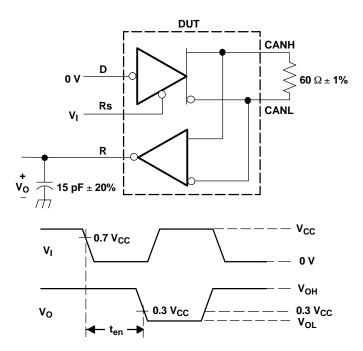
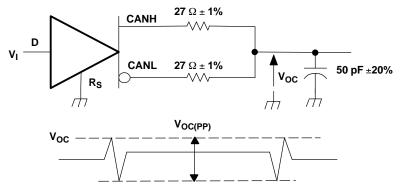


Figure 8. t<sub>en</sub> Test Circuit and Voltage Waveforms





A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  125 kHz, 50% duty cycle,  $t_i \leq$  6ns,  $t_i \leq$  6ns,  $Z_O = 50\Omega$ .

Figure 9. Peak-to-Peak Common Mode Output Voltage

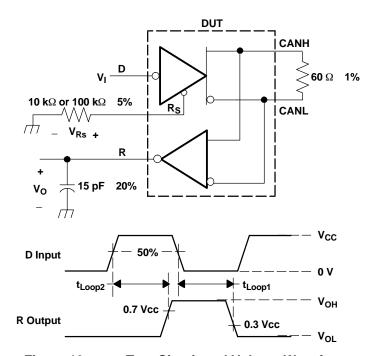


Figure 10.  $t_{\text{LOOP}}$  Test Circuit and Voltage Waveforms



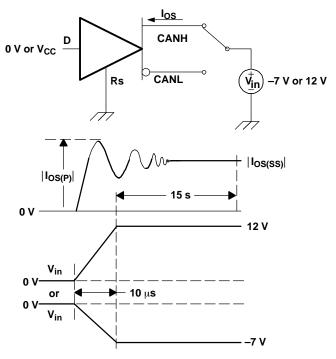
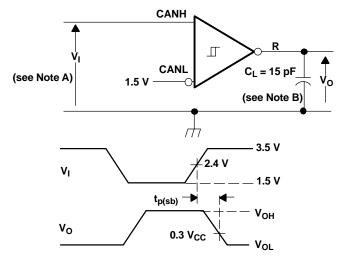


Figure 11. Driver Short-Circuit Test

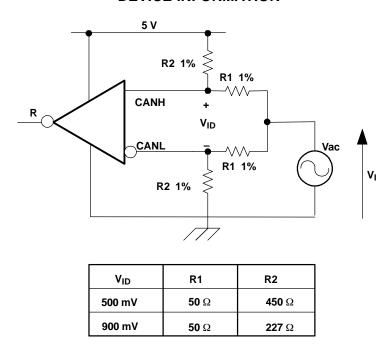


- A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  125 kHz, 50% duty cycle,  $t_{f} \leq$  6ns,  $t_{f} \leq$  6ns,  $Z_{O} = 50\Omega$ .
- B. CL includes instrumentation and fixture capacitance within  $\pm 20\%$ .

Figure 12. Receiver Propagation Delay in Standby Test Circuit and Waveform



## **DEVICE INFORMATION**





A. All input pulses are supplied by a generator having the following characteristics: f < 1.5 MHz,  $T_A = 25$ °C,  $V_{CC} = 5.0$  V.

Figure 13. Common-Mode Input Voltage Rejection Test

## **FUNCTION TABLES**

Table 2. DRIVER

INPUTS	Valtage at B. V	OUTPUTS		BUS STATE	
D	Voltage at R <sub>s</sub> , V <sub>Rs</sub>	CANH	CANL	BUS STATE	
L	V <sub>Rs</sub> < 1.2 V	Н	L	Dominant	
Н	V <sub>Rs</sub> < 1.2 V	Z	Z	Recessive	
Open	X	Z	Z	Recessive	
X	$V_{Rs} > 0.75 V_{CC}$	Z	Z	Recessive	

Table 3. RECEIVER

DIFFERENTIAL INPUTS [V <sub>ID</sub> = V(CANH) - V(CANL)]	OUTPUT R <sup>(1)</sup>	
V <sub>ID</sub> ≥ 0.9 V	L	
0.5V < V <sub>ID</sub> < 0.9 V	?	
V <sub>ID</sub> ≤ 0.5 V	Н	
Open	Н	

(1) H = high level; L = low level; X = irrelevant; ? = indeterminate; Z = high impedance



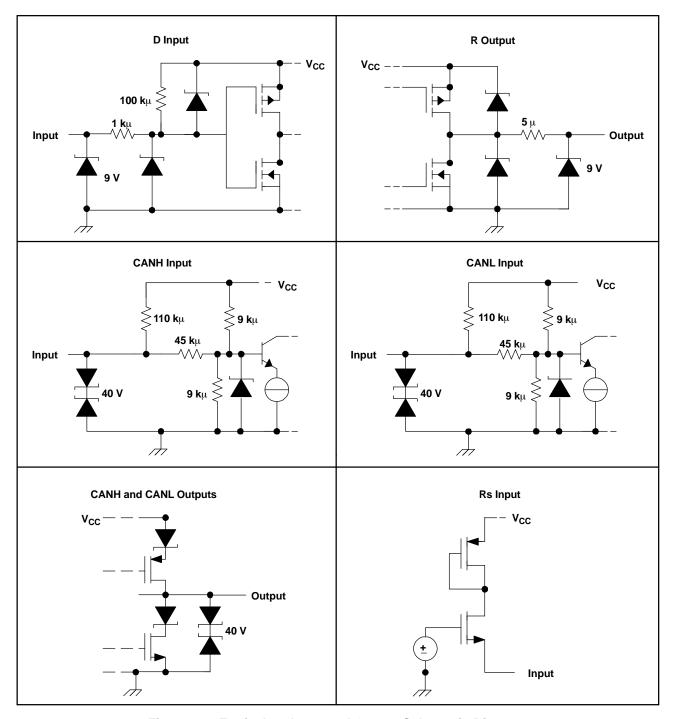


Figure 14. Equivalent Input and Output Schematic Diagrams



## TYPICAL CHARACTERISTICS

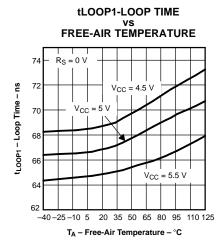


Figure 15.

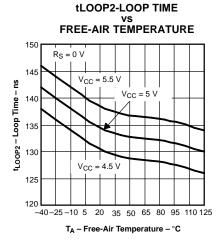


Figure 16.

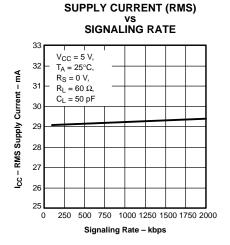


Figure 17.

# DRIVER LOW-LEVEL OUTPUT CURRENT vs LOW-LEVEL OUTPUT VOLTAGE

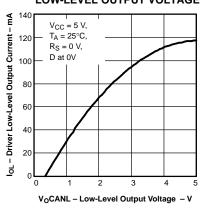


Figure 18.

#### DRIVER HIGH-LEVEL OUTPUT CUR-RENT vs

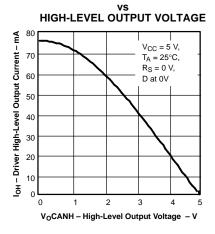


Figure 19.

# DOMINANT DIFFERENTIAL OUTPUT VOLTAGE vs

## FREE-AIR TEMPERATURE

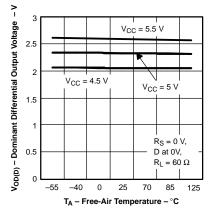
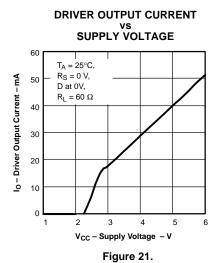
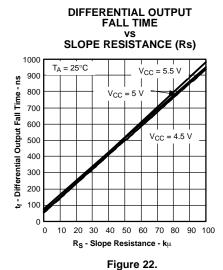
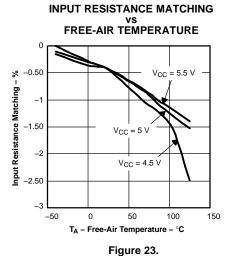


Figure 20.











#### **APPLICATION INFORMATION**

The basics of arbitration require that the receiver at the sending node designate the first bit as dominant or recessive after the initial wave of the first bit of a message travels to the most remote node on a network and back again. Typically, this *sample* is made at 75% of the bit width, and within this limitation, the maximum allowable signal distortion in a CAN network is determined by network electrical parameters.

Factors to be considered in network design include the  $\approx 5$  ns/m propagation delay of typical twisted-pair bus cable; signal amplitude loss due to the loss mechanisms of the cable; and the number, length, and spacing of drop-lines (stubs) on a network. Under strict analysis, variations among the different oscil-

lators in a system also need to be accounted for with adjustments in signaling rate and stub & bus length. Table 2 lists the maximum signaling rates achieved with the SN65HVD251 in high-speed mode with several bus lengths of category 5, shielded twisted pair (CAT 5 STP) cable.

Table 4. Maximum Signaling Rates for Various Cable Lengths

BUS LENGTH (m)	SIGNALING RATE (kbps)		
30	1000		
100	500		
250	250		
500	125		
1000	62.5		

The ISO 11898 Standard specifies a maximum bus length of 40 m and maximum stub length of 0.3 m with a maximum of 30 nodes. However, with careful design, users can have longer cables, longer stub lengths, and many more nodes on a bus. (Note: Non-standard application may come with a trade-off in signaling rate.) A large number of nodes requires a transceiver with high input impedance such as the HVD251.

The Standard specifies the interconnect to be a single twisted-pair cable (shielded or unshielded) with  $120\Omega$  characteristic impedance (Zo). Resistors equal to the characteristic impedance of the line terminate both ends of the cable to prevent signal reflections. Unterminated drop-lines connect nodes to the bus and should be kept as short as possible to minimize signal reflections.

Connectors, while not specified by the Standard should have as little effect as possible on standard operating parameters such as capacitive loading. Although unshielded cable is used in many applications, data transmission circuits employing CAN transceivers are usually used in applications requiring a rugged interconnection with a wide common-mode voltage range. Therefore, shielded cable is recommended in these electronically harsh environments, and when coupled with the Standard's –2-V to 7-V common-mode range of tolerable ground noise, helps to ensure data integrity. The HVD251 enhances the Standard's insurance of data integrity with an extended –7-V to 12-V range of common-mode operation.

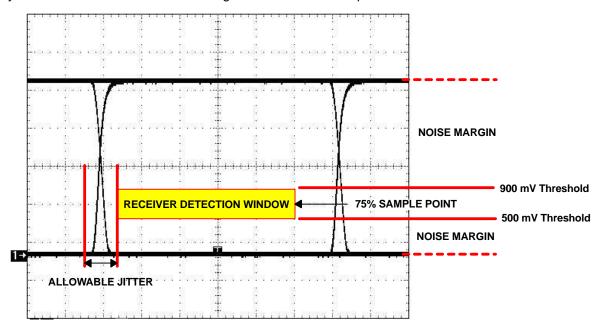


Figure 24. Typical CAN Differential Signal Eye-Pattern



An eye pattern is a useful tool for measuring overall signal quality. As displayed in Figure 24, the differential signal changes logic states in two places on the display, producing an eye. Instead of viewing only one logic crossing on the scope, an entire bit of data is brought into view. The resulting eye pattern includes all of the effects of systemic and random distortion, and displays the time during which a signal may be considered valid.

The height of the eye above or below the receiver threshold voltage level at the sampling point is the noise margin of the system. Jitter is typically measured at the differential voltage zero-crossing during the logic state transition of a signal. Note that jitter present at the receiver threshold voltage level is considered by some to be a more effective representation of the jitter at the input of a receiver.

As the sum of skew and noise increases, the eye closes and data is corrupted. Closing the width decreases the time available for accurate sampling, and lowering the height enters the 900 mV or 500 mV threshold of a receiver.

Different sources induce noise onto a signal. The more obvious noise sources are the components of a transmission circuit themselves; the signal transmitter, traces & cables, connectors, and the receiver. Beyond that, there is a termination dependency, cross-talk from clock traces and other proximity effects, VCC & ground bounce, and electromagnetic interference from near-by electrical equipment.

The balanced receiver inputs of the HVD251 mitigate most all sources of signal corruption, and when used with a quality shielded twisted-pair cable, help insure data integrity.

#### Typical Application

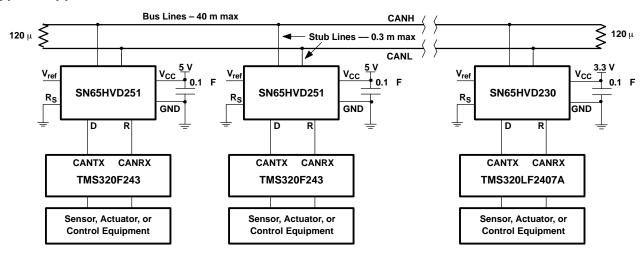


Figure 25. Typical HVD251 Application

## P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

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# D (R-PDSO-G8)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



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